

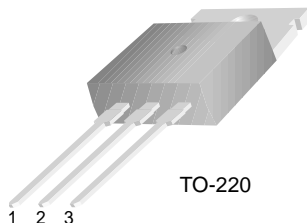
MBRP3010N

Features

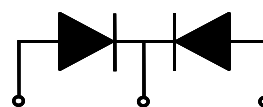
- Low forward voltage drop
- High frequency properties and switching speed
- Guard ring for over-voltage protection

Applications

- Switched mode power supply
- Freewheeling diodes



TO-220



1. Anode 2.Cathode 3. Anode

SCHOTTKY BARRIER RECTIFIER

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	100	V
V_R	Maximum DC Reverse Voltage	100	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 105^\circ\text{C}$	30	A
I_{FSM}	Non-repetitive Peak Surge Current (per diode) 60Hz Single Half-Sine Wave	250	A
T_J, T_{STG}	Operating Junction and Storage Temperature	-65 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case (per diode)	1.7	$^\circ\text{C/W}$

Electrical Characteristics (per diode)

Symbol	Parameter	Value	Units
V_{FM}^*	Maximum Instantaneous Forward Voltage		V
	$I_F = 15\text{A}$	$T_C = 25^\circ\text{C}$	0.85
	$I_F = 15\text{A}$	$T_C = 125^\circ\text{C}$	0.67
	$I_F = 30\text{A}$	$T_C = 25^\circ\text{C}$	1.05(TYP.)
	$I_F = 30\text{A}$	$T_C = 125^\circ\text{C}$	0.80
I_{RM}^*	Maximum Instantaneous Reverse Current		mA
	@ rated V_R	$T_C = 25^\circ\text{C}$	1
		$T_C = 125^\circ\text{C}$	20

* Pulse Test: Pulse Width=300 μs , Duty Cycle=2%

Typical Characteristics

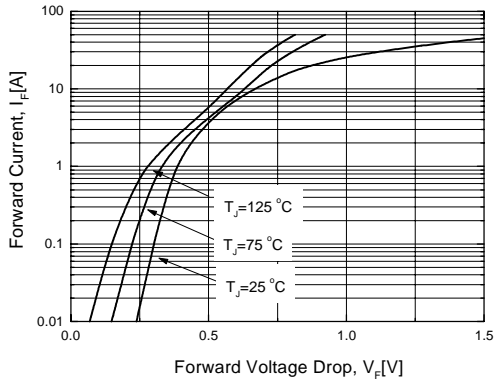


Figure 1. Typical Forward Voltage Characteristics (per diode)

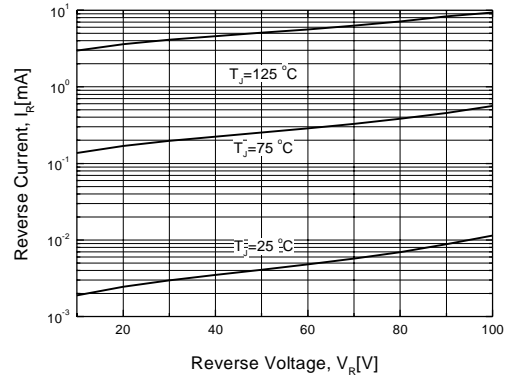


Figure 2. Typical Reverse Current vs. Reverse Voltage (per diode)

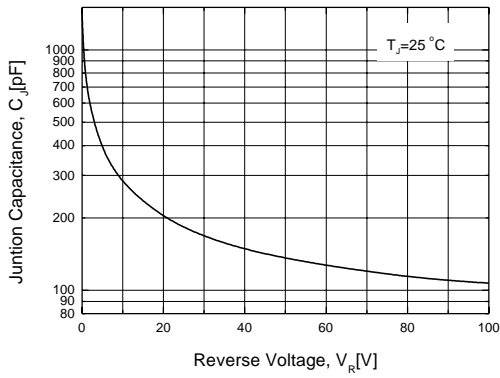


Figure 3. Typical Junction Capacitance (per diode)

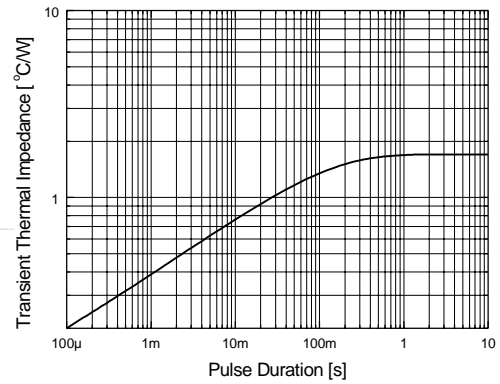


Figure 4. Thermal Impedance Characteristics (per diode)

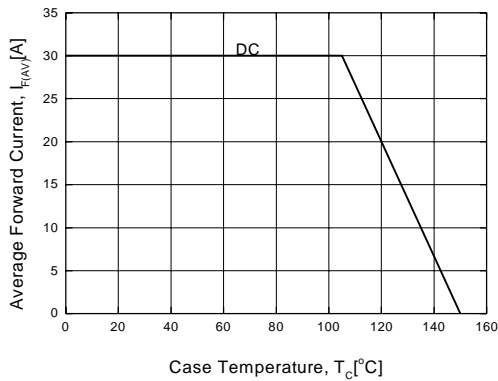


Figure 5. Forward Current Derating Curve

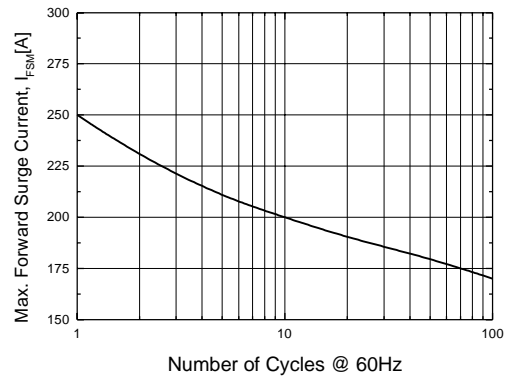
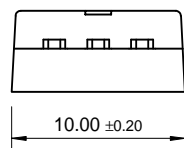
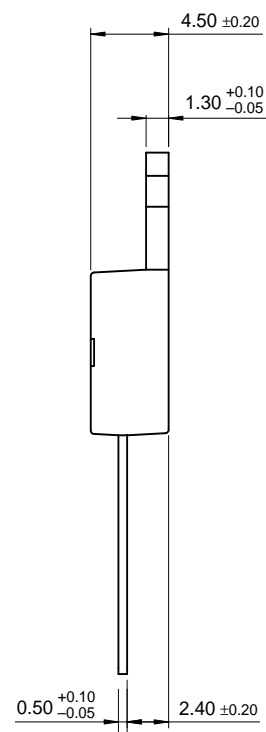


Figure 6. Non-Repetitive Surge Current (per diode)

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Technical drawing of a 2.54TYP connector. The drawing shows a side view of the component with various dimensions in millimeters. The overall width is 9.90 ±0.20. The top section has a width of 8.70 and a central hole with a diameter of ø3.60 ±0.10. The top section has a height of 2.80 ±0.10. The middle section has a height of 15.90 ±0.20, with a sub-section of 3.70. The bottom section has a height of 13.08 ±0.20, with a sub-section of 1.00. The bottom section has a width of 1.27 ±0.10 and 1.52 ±0.10. The bottom section has a 45° angle. The bottom section has a width of 0.80 ±0.10. The bottom section has a height of 10.08 ±0.30. The bottom section has a height of 18.95 MAX. The bottom section has a height of 9.20 ±0.20. The bottom section has a height of 1.30 ±0.10. The bottom section has a height of 1.70. The bottom section has a height of 1.46. The bottom section has a height of 3.00. The bottom section has a height of 2.54TYP [2.54 ±0.20]. The bottom section has a height of 2.54TYP [2.54 ±0.20].



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